

102903
01919 U.S. PTO

Attorney's Docket No. H1508

Express Mail No. ER145706569US

22386 U.S. PTO
10/697214
102903

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Christine Hau-Riege, et al.

Group Art Unit: Unknown

Serial No.: 60/501,445

Examiner: Unknown

Filed: Herewith

Title: SEMICONDUCTOR COMPONENT AND METHOD FOR PRECLUDING STRESS-
INDUCED VOID INFORMATION IN THE SEMICONDUCTOR COMPONENT

Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

NEW APPLICATION TRANSMITTAL

Transmitted herewith for filing is the patent application of Inventor(s):

Christine Hau-Riege
John Sanchez, Jr.
Amit Marathe

For:

SEMICONDUCTOR COMPONENT AND METHOD OF MANUFACTURE

1. Type of Application

This new application is for a(n)

- ☒ Original (nonprovisional)
- ☐ Design
- ☐ Plant
- ☐ Continuation
- ☐ Continuation-in-part (C-I-P)

Title: SEMICONDUCTOR COMPONENT AND METHOD FOR PRECLUDING STRESS-INDUCED VOID INFORMATION IN THE SEMICONDUCTOR COMPONENT
Inventor(s): Christine Hau-Riege, John Sanchez, Jr., Amit Marathe

2. Benefit of Prior U.S. Application(s) (35 U.S.C. 119(e), 120, or 121)

- ☒ The new application being transmitted claims the benefit of prior U.S. application(s). **Enclosed are added pages for new application transmittal where benefit of prior U.S. application(s) claimed.**

3. Papers Enclosed

A. Required for filing date under 37 CFR § 1.53(b) (Regular) or 37 CFR § 1.153 (Design) Application

14 Pages of specification

5 Pages of claims

4 Sheets of drawing

- ☒ formal
☐ informal
☐ The enclosed drawing(s) are photograph(s), and there is also attached a "Petition to Accept Photograph(s) as Drawing(s)." 37 CFR 1.84(b)

B. Other Papers Enclosed

4 Pages of declaration and power of attorney

1 Pages of abstract

Other

4. Additional papers enclosed

- ☐ Amendment to claims
☐ Cancel in this applications claims _____ before calculating the filing fee.
☐ Add the claims shown on the attached amendment. (Claims added have been numbered consecutively following the highest numbered original claims.)
- ☐ Preliminary Amendment
☒ Information Disclosure Statement (37 CFR 1.98)

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- ☒ Form PTO-1449 (PTO/SB/08A and 08B)
- ☐ Declaration of Biological Deposit
- ☐ Submission of "Sequence Listing" computer readable copy and/or amendment pertaining thereto for biotechnology invention containing nucleotide and/or amino acid sequence.
- ☐ Authorization of Attorney(s) to Accept and Follow Instructions from Representative
- ☐ Special Comments
- ☐ Other

5. Declaration or oath

- ☒ Enclosed
Executed by
 - ☒ inventor(s).
 - ☐ legal representative of inventor(s). (37 CFR 1.42 or 1.43)
 - ☐ joint inventor or person showing a proprietary interest on behalf of inventor who refused to sign or cannot be reached.
 - ☐ This is the petition required by 37 CFR 1.47 and the statement required by 37 CFR 1.47 is also attached. See item 13 below for fee.
- ☐ Not enclosed.
 - ☐ Application is made by a person authorized under 37 CFR 1.41(c) on behalf of *all* the above named inventor(s).

6. Power of Attorney

- ☐ Enclosed
 - ☐ Combined with Oath executed by inventors
 - ☐ Separate Power of Attorney executed by owner
 - ☐ 37 CFR § 3.73(b) Declaration

7. Inventorship Statement

The inventorship for all the claims in this application are:

- ☒ The same.
- ☐ Not the same. An explanation, including the ownership of the various claims at the time the last claimed invention was made,
 - ☐ is submitted.
 - ☐ will be submitted.

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8. Language

- ☒ English
☐ Non-English
☐ The attached translation includes a statement that the translation is accurate. 37 CFR 1.52(d).

9. Assignment

- ☒ An assignment of the invention to Advanced Micro Devices, Inc.
☒ is attached. A separate
☐ "Cover Sheet for Assignment Document Accompanying New Patent Application" or
☒ Form PTO 1595 is also attached.
☐ will follow.

10. Fee Calculation (37 CFR 1.16)

A. Regular application

CLAIMS AS FILED					
	Number Filed	Number Extra		Rate	Basic fee 37 CFR 1.16(a) \$770.00
Total Claims (37 CFR 1.16(c))	22- 20 =	2	x	\$18.00	\$36.00
Independent Claims (37 CFR 1.16(b))	3 - 3 =	0	x	\$86.00	\$0.00
Multiple dependent Claim(s), if any (37 CFR 1.16(d))	0		x	\$280.00	\$0.00

- ☐ Amendment canceling extra claims is enclosed.
☐ Amendment deleting multiple-dependencies is enclosed.
☐ Fee for extra claims is not being paid at this time.

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Filing Fee Calculation (\$770.00) \$ 806.00

B. ☐ Design application (\$320.00 - 37 CFR 1.16(f))
Filing Fee Calculation \$ _____

☐ Plant application (\$490.00 - 37 CFR 1.16(g))
Filing Fee Calculation \$ _____

11. Request for International-Type Search (37 CFR 1.104(d))

☐ Please prepare an international-type search report for this application at the time when national examination on the merits takes place.

12. Fee Payment Being Made at this Time

☐ Not Enclosed
☐ No filing fee is to be paid at this time.

☒ Enclosed

☒ Filing fee \$806_____

☒ Recording assignment (\$40.00; 37 CFR 1.21(h))
(See attached "COVER SHEET FOR ASSIGNMENT
ACCOMPANYING NEW APPLICATION".) \$40.00

☐ Petition fee for filing by other than all the inventors
or person on behalf of the inventor where inventor
refused to sign or cannot be reached
(\$130.00; 37 CFR 1.47 and 1.17(i)) \$0.00

☐ For processing an application with a specification
in a non-English language (\$130.00; 37 CFR 1.52(d)
and 1.17(k)) \$0.00

☐ Processing and retention fee (\$130.00; 37 CFR
1.53(d) and 1.21(i)) \$0.00

☐ Fee for international-type search report

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(\$40.00; 37 CFR 1.21(e))

\$0.00

Total fees enclosed

\$846.00

13. Method of Payment of Fees

☒ Check in the amount of \$846.00

☐ Charge Account No. 50-2173 in the amount of \$_____

A duplicate of this transmittal is attached.

14. Authorization to Charge Additional Fees

☒ The Commissioner is hereby authorized to charge additional fees by this paper and during the entire pendency of this application to Account No. 50-2173

15. Instructions as to Overpayment

☒ Credit Account No. 50-2173

☐ Refund

16. Incorporation by Reference of Added Pages

☒ Plus Added Pages for New Application Transmittal Where Benefit of Prior U.S. Application(s) Claimed

Number of pages added 3

☐ Plus Added Pages for Papers Referred to in Item 4 Above

Number of pages added _____

☐ Plus Added Pages Deleting Name(s) of Inventor(s) Named in Prior Application(s) Who is/are No Longer Inventor(s) of the

Title: SEMICONDUCTOR COMPONENT AND METHOD FOR PRECLUDING STRESS-INDUCED VOID INFORMATION IN THE SEMICONDUCTOR COMPONENT
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Subject Matter Claimed in this Application

Number of pages added _____

- ☐ Plus "Assignment Cover Letter Accompanying New Application"

Number of pages added _____

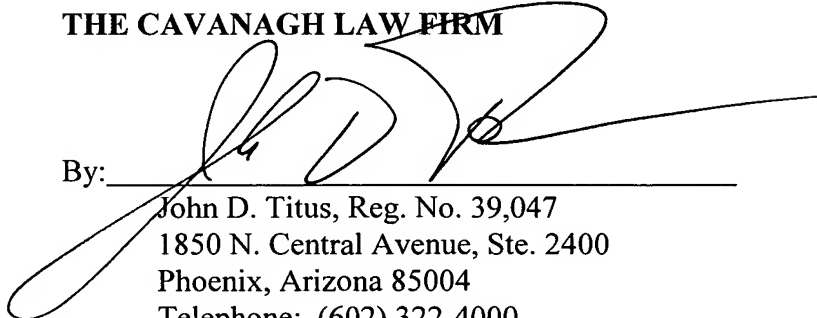
17. Statement Where no Further Pages Added

- ☐ This transmittal ends with this page.

Respectfully submitted,

THE CAVANAGH LAW FIRM

Dated: 29 Oct 2003

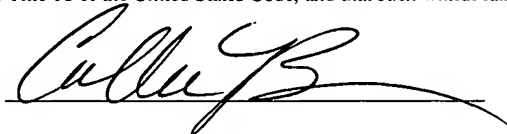
By: 

John D. Titus, Reg. No. 39,047
1850 N. Central Avenue, Ste. 2400
Phoenix, Arizona 85004
Telephone: (602) 322-4000
Facsimile: (602) 322-4101

CERTIFICATE OF EXPRESS MAILING UNDER 37 C.F.R. 1.10.

I hereby certify that this document (and any as referred to as being attached or enclosed) is being deposited with the United States Postal Service as "Express Mail Post Office to Addressee" service, mailing label No. **ER145706269US** on October 29, 2003 and addressed to Box Patent Application, Assistant Commissioner for Patents, Washington, D.C. 20231.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



**ADDED PAGES FOR APPLICATION TRANSMITTAL WHERE
BENEFIT OF PRIOR U.S. APPLICATION(S) CLAIMED**

18. Relate Back

☒ Amend the specification by inserting, before the first line, the following sentence:

A. 35 U.S.C. 119(e)

☒ "This application claims the benefit of U.S. Provisional Application No(s):

APPLICATION NO(S).

60/501,445

/

/

FILING DATE

September 9, 2003

B. 35 U.S.C. 120, 121 and 365(c)

☐ "This application is a

☐ continuation

☐ continuation-in-part

☐ divisional

of copending application(s)

☐ application number / / filed on "

☐ International Application filed on
and which designated the U.S."

☐ "The non-provisional application designated above, namely, application / / filed claims the benefit of U.S. Provisional Application No(s):

APPLICATION NO(S).

/

/

/

FILING DATE

☐ Where more than one reference is made above, please combine all references into one sentence.

19. Relate Back - 35 U.S.C. 119 Priority Claim for Prior Application

The prior U.S. application(s), including any prior International Application designating the U.S., identified above in item 17B, in turn itself claim(s) foreign priority(ies) as follows:

Country	Appln. No.	Filed on
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The certified copy(ies) has (have)

☐ been filed on in prior application / / , which was filed on .

☐ is (are) attached.

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20. Maintenance of Copendency of Prior Application

- A. ☐ Extension of time in prior application
☐ A petition, fee and response extends the term in the pending **prior** application until _____
☐ A **copy** of the petition filed in prior application is attached. .
- B. ☐ Conditional Petition for Extension of Time in Prior Application
☐ A conditional petition for extension of time is being filed in the pending **prior** application.
☐ A **copy** of the conditional petition filed in the prior application is attached.

21. Further Inventorship Statement Where Benefit of Prior Application(s) Claimed

- (a) ☒ This application discloses and claims only subject matter disclosed in the prior application whose particulars are set out above and the inventor(s) in this application are
☒ the same.
☐ less than those named in the prior application. It is requested that the following inventor(s) identified for the prior application be deleted:

- (b) ☒ This application discloses and claims additional disclosure by amendment and a new declaration or oath is being filed. With respect to the prior application, the inventor(s) in this application are
☒ the same.
☐ the following additional inventor(s) has (have) been added:

- (c) ☒ The inventorship for all the claims in this application are
☒ the same.
☐ not the same. An explanation, including the ownership of the various claims at the time the last claimed invention was made
☐ is submitted.
☐ will be submitted.

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22. Abandonment of Prior Application

- ☐ Please abandon the prior application at a time while the prior application is pending, or when the petition for extension of time or to revive in that application is granted, and when this application is granted a filing date, so as to make this application copending with said prior application.

23. Petition for Suspension of Prosecution for the Time Necessary to File an Amendment

- ☐ There is provided herewith a Petition to Suspend Prosecution for the Time Necessary to File an Amendment (New Application Filed Concurrently).

24. Small Entity (37 CFR 1.28(a))

- ☐ Applicant has established small entity status by the filing of a statement in application [NUMBER] filed on [DATE] on which priority is claimed.
☐ A copy of the statement previously filed is included.

25. Notification in Parent Application of this Filing

- ☐ A notification of the filing of this
☐ continuation
☐ continuation-in-part
☐ divisional
is being filed in the parent application, from which this application claims priority under 35 U.S.C. 120.

Respectfully submitted,

THE CAVANAGH LAW FIRM

Dated: 29 Oct 2003

By: 

John D. Titus, Reg. No. 39,047
1850 N. Central Avenue, Ste. 2400
Phoenix, Arizona 85004
Telephone: (602) 322-4000
Facsimile: (602) 322-4101

CAVPHXDB:1049057.1

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

**NONPUBLICATION REQUEST
UNDER
35 U.S.C. 122(b)(2)(B)(i)**

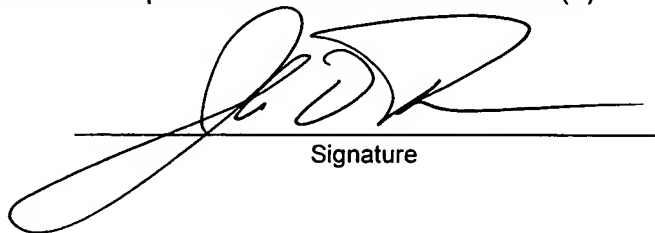
First Named Inventor	Christine Hau-Riege, et al.
Title	SEMICONDUCTOR COMPONENT AND METHOD FOR PRECLUDING STRESS-INDUCED VOID INFORMATION IN THE SEMICONDUCTOR
Attorney Docket Number	H1508

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

I hereby request that the attached application not be published under 35 U.S.C. 122(b).

29 oct 2003

Date



Signature

602-322-4074

Telephone number

John D. Titus

Typed or printed name

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

This collection of information is required by 37 CFR 1.213(a). The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 6 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 (1-800-786-9199) and select option 2.